NOTES: UNLESS OTHERWISE SPECIFIED

1. MAT'L: Copper clad plated sheet per MIL-P-13949/4, Type GFM,
   A. Copper Weight:
      a) Outer Layers 1.5 OZ.
      b) Inner Plane Layers 1 OZ.
      c) Inner Signal Layers 1 OZ.
   B. Laminate using Pre-Preg Material Per MIL-P-13949/12, Type PC-GF. Tg minimum 170 deg C.
2. Overall Board thickness to be .093 +/- .009.
3. Unless otherwise specified all hole dimensions apply after platting. All plated through holes to have a minimum of .001 copper.
4. All holes shall be located within .003 diameter of true position. Layer to layer registration shall be within .005. All holes surrounded by land shall have a minimum annular ring of .001. Tangency on holes with breakout is acceptable.
5. Conductor widths and spacing shall be within +/- 20% of artwork originals.
6. Apply solder mask (liquid photo imageable) over bare copper, solder mask to be per IPC-SM-84D, Type B, Class 3, Color: Transparent Green. All exposed conductive surfaces to be solder coated.
7. Ware or twist of board shall not exceed .0075 inch per inch.

NOTES: UNLESS OTHERWISE SPECIFIED

1. This is a static sensitive assembly- use static eliminating measures during assembly and handling.
2. Manufacture to IPC 610A workmanship standards.
3. Trim component leads within .062 from solder side of PWA with exception of indicated area, which must be trimmed to .010 +/- .010
4. Apply part number and serial number labels in areas shown.
5. Install item 19 (120-1032-001 heat sink as follows:
   A. Clean bottom surface of heat sink and mounting
   B. Apply sufficient amount of Item 21 (120-1031-001), epoxy tube, to bottom of heat sink.
   C. Apply Item 21, activator tube to mounting surface of Pentium Module
   D. Mount heat sink onto Pentium Module and allow to sit for 30 seconds.
6. Discard nylon washer supplied with Item 16 (120-9958-002)

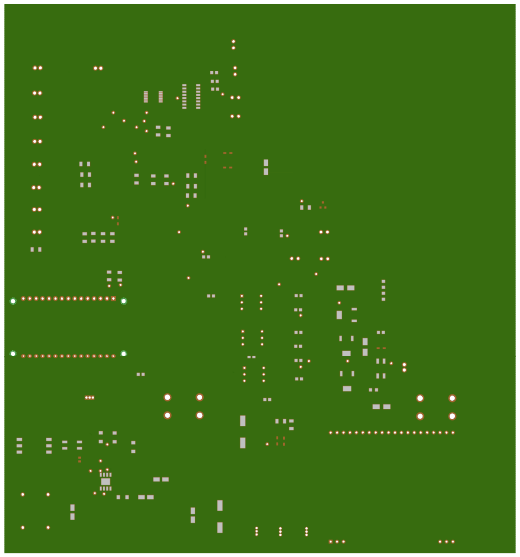
Output: IPC-2581 Files
Type : IPC2581
From : Variant [[No Variations]] of Project [Free Documents]
Generated File[stiralka plata.cvg]

Files Generated : 1
Documents Printed : 0

Finished Output Generation At 21:38:09 On 27.06.2024

Drill Chart

Size	Sym	Qty	Plated	Tolerance
0.028	+	18	Yes	+/-0.003
0.028	X	74	Yes	+0/-0.028
0.031	⊥	26	Yes	+/-0.003
0.033	◇	12	Yes	+/-0.003
0.035	⧖	30	Yes	+/-0.003
0.039	⊠	14	Yes	+/-0.003
0.039	⊕	8	Yes	+0/-0.039
0.046	⊗	40	Yes	+0/-0.046
0.081	⊞	8	Yes	+0/-0.081
0.087	⊠	8	Yes	+0/-0.087
0.115	◈	8	No	+/-0.002
Total		246		



UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES ARE IN INCHES AND APPLY TO THE FINISHED PART

TOLERANCE ON:		
1%	1%	1%

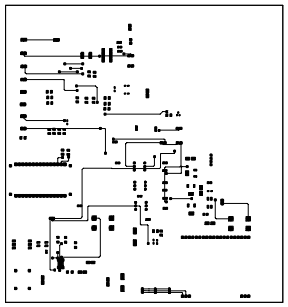
MATL	N/A		
HARD	CLASS 1	CASE DEPTH	1.65
SURF TREAT	FR-4		

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

ЧЕРТЁЖПЛАТЫ МАЛЕНЬКИЙ	YES
NEXT ASSY	USED ON
APPLICATION	

3D PCB View

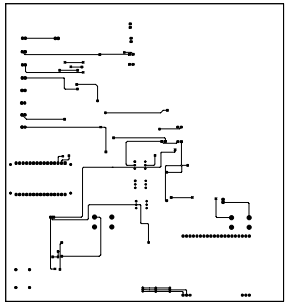
DRAWN	DATE 27.06.24	TITLE	stiralka plata
ENGINEER IGISHEV A.M.	DATE		
CHECKED MOLGANOV A.A.	DATE		
APPROVED N/A	DATE	SIZE C / CAGE CODE / DWG NO / REV A	
ISSUED IGISHEV A.M.	DATE	SCALE 1 : 1	SHEET 1 OF 1



DRILL PATTERN

СХЕМАТИЧНОЕ РАСПОЛОЖЕНИЕ КОМПОНЕНТОВ

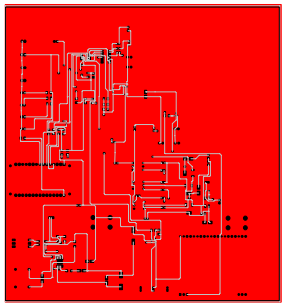
Данный чертеж описывает положение всех элементов на печатной плате в соответствии с физическими рамерами печатной платы и ее формы



BOARD OUTLINE

СЛОЙ ПЕРЕХОДНЫХ ОТВЕРСТИИ И ГАБАРИТА ПЕЧАТНОЙ ПЛАТЫ

Данный чертеж описывает положений отверстий и переходных положений относительно общего описания всех механическтх ианипуляций с печатной платой(сверление, размещение компонентов и тд.)



DRILL PATTERN

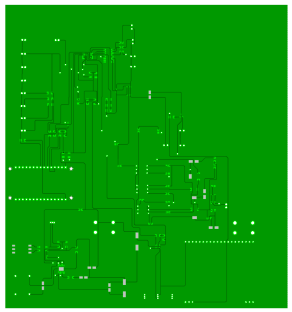
ВЕРХНИЙ СЛОЙ ПЕЧАТНОЙ ПЛАТЫ И ЕЕ ПРОВОДНИКИ

Данный чертеж описывает положение проводников, отверстии и переходных положении относительно общего габарита печатной платы и слой меди(верхний слой)

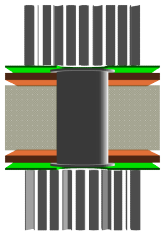
BOARD OUTLINE

ОБЩИЙ СЛОЙ ГАБАРИТА ПЕЧАТНОЙ ПЛАТЫ

Габарит печатной платы представляет собой графический примитив описания общего слоя печатной платы и формы печатной платы.



3D PCB View

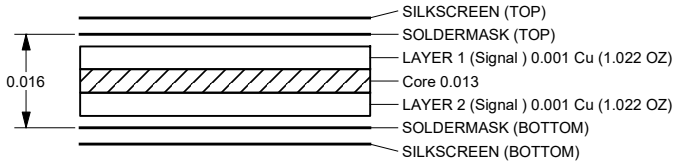


3D Rigid-Flex Stackup

КАРТА СЛОЕВ

Оранжевый слой- медный слой печатной платы
Желтый слой - габариты элементов размещенныйх на печатной плате
Зеленый слой - паяльная маска печатной платы

LAYER STACK-UP



UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES ARE IN INCHES AND APPLY TO THE FINISHED PART			
TOLERANCE ON:			
1%	1%	1%	
MATL	N/A		
HARD	CLASS 1	CASE DEPTH	1.65
SURF TREAT	FR-4		

Variant Legend

	Installed
	Uninstalled
	Substituted

Process Step Chart

Color	Ref. Des.	Part Name	Description
	ProcessStep	PartsList.PartName	ProcessSteps.GroupName

Material Name	Material Type	Qty
Copper	Conductor	2
FR-4	Dielectric Rigid Core	1
Silkscreen White	Silkscreen	AR
Solder Resist	SolderMask	AR
Solderpaste	Solderpaste	2

DRAWN	DATE 20.06.24	TITLE	stiralka plata
ENGINEER IGISHEV A.M.	DATE		
CHECKED MOLGANOV A.A.	DATE		
APPROVED N/A	DATE	SIZE C / CAGE CODE / DWG NO	REV A
ISSUED IGISHEV A.M.	DATE	SCALE 1 : 1	SHEET 1 OF 1